

General Description

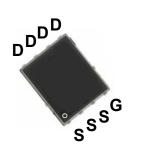
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

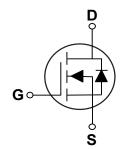
BV _{DSS}	R _{DS(ON)}	I _D
65 V	4.4 mΩ	95 A

Features

- $R_{DS(ON)} \leq \overline{4.4m\Omega} \overline{@V_{GS}} = 10V$
- · Fast switching
- · Improved dv/dt capability
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- Networking
- · Load Switch
- LED applications

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	65	V	
V_{GS}	Gate-Source Voltage	±20	V	
1	Drain Current – Continuous (T _C =25°C)	95	Α	
I _D	Drain Current – Continuous (T _C =100°C)	60	Α	
I _{DM}	Drain Current – Pulsed (NOTE 1)	380	Α	
EAS	Single Pulse Avalanche Energy (NOTE 2)	151.3	mJ	
IAS	Single Pulse Avalanche Current (NOTE 2)	55	Α	
P_{D}	Power Dissipation (T _C =25°C)	96	W	
ГD	Power Dissipation – Derate above 25°C	0.77	W/°C	
T _J	Storage Temperature Range	-50 to 150	°C	
T _{STG}	Operating Junction Temperature Range	-50 to 150	°C	
/larking Code		NG4P4		

Thermal Characteristics					
Symbol	Parameter	Тур.	Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		1.3	°C/W	





Electrical Characteristics (T_{.1}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	65			V
I _{DSS} Dra	IDrain-Source Leakage Current	V_{DS} =60V , V_{GS} =0V , T_J =25°C			1	uA
		V_{DS} =48V , V_{GS} =0V , T_{J} =85 $^{\circ}$ C			10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V _{GS} =10V , I _D =20A		3.7	4.4	mΩ
		V _{GS} =4.5V , I _D =15A		5.8	7.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0	1.6	2.5	V
gfs	Forward Transconductance	V_{DS} =10V , I_{D} =3A		10		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} =48V , V _{GS} =10V , I _D =30A		36	54	
Q_gs	Gate-Source Charge	V_{DS} -46V, V_{GS} -10V, I_{D} -30A (NOTE 3 \ 4)		4.7	7.1	nC
Q_{gd}	Gate-Drain Charge	(NOTE 3 * 4)		13.5	20	
$T_{d(on)}$	Turn-On Delay Time	V_{DD} =48V , V_{GS} =10V , R_{G} =6 Ω , I_{D} =1A (NOTE 3 \cdot 4)		10.2	15	
T _r	Rise Time			16	24	nS
$T_{d(off)}$	Turn-Off Delay Time			42	63	113
T_f	Fall Time			38	57	
C _{iss}	Input Capacitance	V _{DS} =48V , V _{GS} =0V , F=1MHz		1675	2510	
C _{oss}	Output Capacitance			322	485	pF
C _{rss}	Reverse Transfer Capacitance			14	25	
R_g	Gate resistance	V _{GS} =0V , V _{DS} =0V , F=1MHz		1.2		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V,Force Current			95	Α
I _{SM}	Pulsed Source Current	V _G -V _D -0V, Force Current			190	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V
t _{rr}	Reverse Recovery Time (NOTE 3)	V _R =50V , I _S =10A ,		54		nS
Q_{rr}	Reverse Recovery Charge (NOTE 3)	di/dt=100A/us , T _J =25°C		67		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =55A, R_{G} =25 Ω , Starting T_{J} =25 $^{\circ}$ C.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.





Characteristics Curves

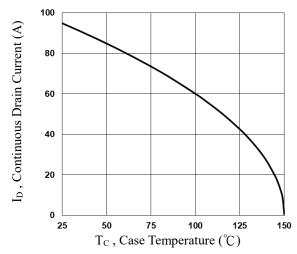


Fig.1 Continuous Drain Current vs. Tc

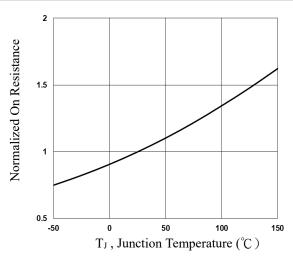


Fig.2 Normalized RDSON vs. TJ

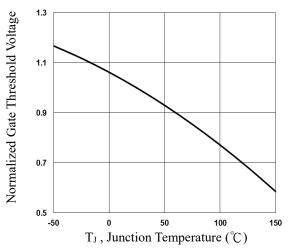


Fig.3 Normalized Vth vs. T_J

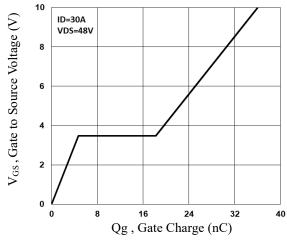


Fig.4 Gate Charge Characteristics

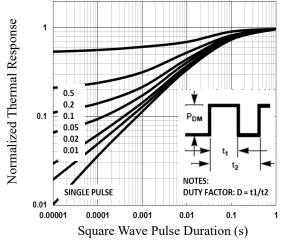


Fig.5 Normalized Transient Impedance

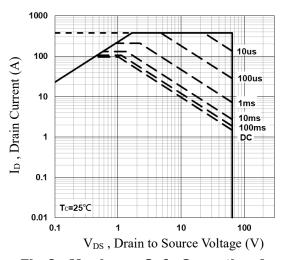
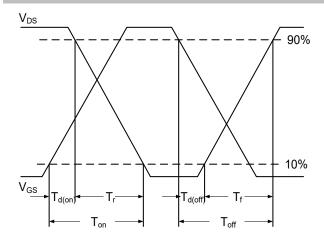


Fig.6 Maximum Safe Operation Area





Characteristics Curves



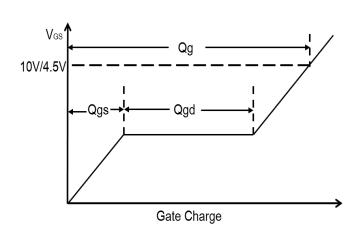
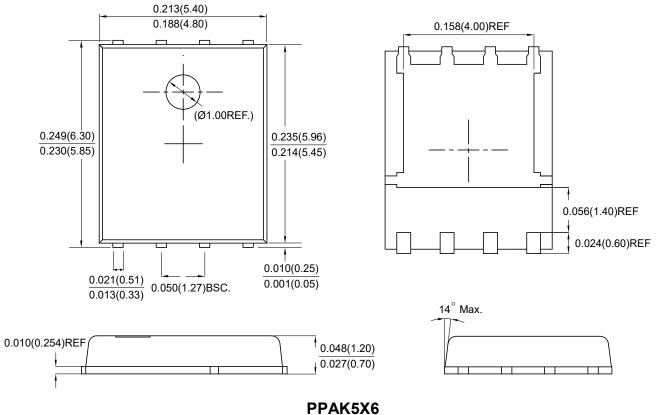


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

Package Outline Dimensions



Dimensions in inches and (millimeters)





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